

V1.1 Datasheet

N+P 40V MOSFET

FEATURES

- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

Application

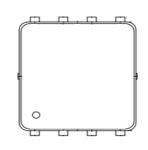
- Portable Devices
- ●Consumer Electronics

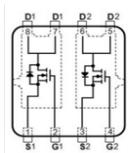
Mechanical

●Case:DFN5060 Package

PRODUCTY SUMMARY V_{DS} RDS(on) m(Ω) Max V_{DS} 19 @V_{GS}=10.0V V_{DS} 26 @V_{GS}=4.5V V_{DS} 31 @V_{GS}=-10.0V V_{DS} 37 @V_{GS}=-4.5V

DFN5060





Packing Information

Package	Packing
DFN5060	3K/13" Reel

Maximum Ratings (T _A =25°C unless otherwise specified)							
Parameter	Symbol	Lin	Limit				
	Symbol	N-Channel	P-Channel	- Unit			
Gate-Source Voltage	V_{DS}	40	-40	V			
Gate-Source Voltage	V_{GS}	±20	±20	А			
Continuous Drain Current 1)	I _{DSM}	17	-13	А			
Continuous Drain Current 4)	I _D	68	-52	А			
Continuous Drain Current 5)	I _{DM}	101	-80	А			
Maximum Power Dissipation	P_{D}	6	6	W			
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	-55 to 150	°C			

Typical Thermal Resistance						
Parameter Symbol Limit Ur						
Junction-to-Ambient Thermal Resistance 3)	$R_{\theta JA}$	34	°C/W			

Note:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Fused current that based on wire numbers and diameter.
- 3. Guaranteed by design, not subject to production testing.
- 4. The maximum current rating is package limited.
- 5. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keepinitial T_J =25°C.

www.mo-semi.com Revision:V1.1



Electrical Characteristics (TA = 25°C UNLESS OTHERWISE NOTED)						
Characteristics	Symbol	Test Condition	Limits			Unit
			Min	Тур	Max	Offic
	N-	Channel Static				
Drain-Source Breakdown Voltage	B _{VDSS}	V _{GS} =0V, I _D =250uA	40	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250uA$	1.0	1.6	2.0	V
Drain-Source On-State Resistance	R _{DS(on)}	V_{GS} =10.0V, I_{D} =17A	-	15	19	mΩ
		V_{GS} =4.5V, I_D =14A	-	20	26	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} =40V, V_{GS} =0V	1	1	1.0	uA
Gate-Source Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
Drain-Source Diode						
Maximum Continuous Body Diode Forward Current	I _S	-	-	-	1.2	А
Diode Forward Voltage	V_{SD}	I_S =1.0A, V_{GS} =0V	-	-	1.5	V

Electrical Characteristics (T _A = 25°C UNLESS OTHERWISE NOTED)						
Characteristics	Symbol	Test Condition	Limits			l lm:t
			Min	Тур	Max	Unit
P-Channel Static						
Drain-Source Breakdown Voltage	B _{VDSS}	V_{GS} =0V, I_D =-250uA	-40	-	-	V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250uA$	-1.0	-	-3.0	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =-10.0V, I _D =-13A	-	26	31	mΩ
		V _{GS} =-4.5V, I _D =-12A	-	31	37	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V, V _{GS} =0V	-	-	1.0	uA
Gate-Source Leakage Current	I _{GSS}	$V_{GS}=\pm20V, V_{DS}=0V$	-	-	±100	nA
Drain-Source Diode						
Maximum Continuous Body Diode Forward Current	I _S	-	-	-	-1.2	А
Diode Forward Voltage	V _{SD}	I _S =-1.0A, V _{GS} =0V	-	-	-1.5	V

Note:

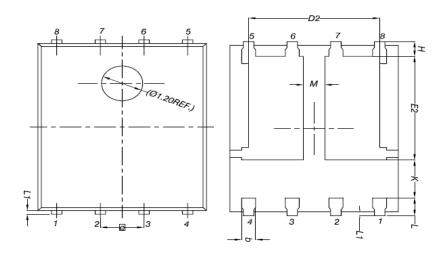
- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keep initial T_J =25°C.
- 4. The maximum current rating is package limited.
- 5. R_{QJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch2 with 2oz.square pad of copper.
- 6. Guaranteed by design, not subject to production testing

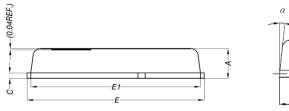
www.mo-semi.com Revision:V1.1



Package Outline Dimensions (inches and millimeters)

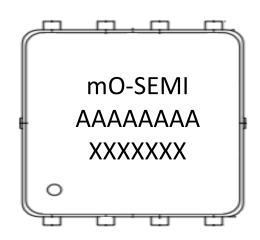
DFN5060							
	Dimensions						
SYMBOL	Millir	neters	Inches				
	Min	Max	Min	Max			
Α	0.90	1.10	0.035	0.043			
b	0.33	0.51	0.013	0.020			
С	0.20	0.30	0.008	0.012			
D1	4.80	5.00	0.189	0.197			
D2	3.61	3.96	0.142	0.156			
E	5.90	6.10	0.232	0.240			
E1	5.70	5.80	0.224	0.228			
E2	3.38	3.78	0.133	0.149			
е	1.27bsc						
Н	0.41	0.61	0.016	0.024			
K	1.100	-	0.043	1			
L	0.51	0.71	0.020	0.028			
L1	0.06	0.20	0.002	0.008			
M	0.50	-	0.020	1			
α	0 °	12 °	-	-			







Marking Information



First line = Company name

AAAAAAAA = Product number

XXXXXXX = Tracking number

Fourth line = Pin1 Point

Motive reserves the right to make changes without further notice to any products herein. Motive makes no warranty representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motive assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in Motive data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motive does not convey any license under its patent rights nor the rights of others. Motive products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motive product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motive products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motive and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims costs damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motive was negligent regarding the design or manufacture of the part.

www.mo-semi.com Revision:V1.1